

Copper Foam

Item Number: BC-25



Introduction

Copper foam has good thermal conductivity and can be widely used for heat conduction and heat dissipation of motors/electrical appliances and electronic components.

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Aperture:	0.1mm-10mm (5-130ppi)
Porosity:	50%-98%
Through hole rate:	≥98%
Number of holes in inches:	110 (110PPI)
Bulk density:	0.1-0.8g/cm ³
Surface density G/M ² :	280-3000(±30-200)
Thickness (MM):	0.1~40(0.05~1.0)
Number of holes PPI:	13~1300(±5~10)
Length/Width/Thickness Dimensions (MM):	70≤length and width